

Appl. No. 10/758,822  
Amdt. Dated March 20, 2006  
Reply to Office Action of September 21, 2005

Docket No. CE11518JGN

**Amendments to the Drawings:**

Applicant includes herewith a replacement drawing sheet for the first drawing sheeting including FIGs. 1-3. Applicant has corrected the duplicate use of reference numeral 106 in FIG.

1. The replacement sheet is so designated at the top margin.

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### **Claim Status**

Claims 1, 3, 4, 6, 13, 17, 24, 26, 27, and 30 have been rewritten. Claims 7 and 23 have been cancelled. Claims 1-6, 8-22, and 24-31 remain in the application.

### **REMARKS/ARGUMENTS**

The claims have been rewritten by incorporating the subject matter of claim 7 into independent claims 1, 13, and 24. Claim 7 was rejected only under 35 USC 112, second paragraph, as being indefinite, and not on any other substantive grounds.

In rejecting claim 7, Examiner took issue with the ratio established by Applicant, and pointed out that the ratio contradicts what is stated in the Background section of the application at page 2, lines 3-4. As this is the background section, Applicant is reciting known principles for avoiding solder shorts between solder pads. It is true that, using prior art methods, it was preferable to reduce the paste thickness to space ratio due to solder spread. However, as recited by Applicant at page 10, lines 12-17. Furthermore, the example given at page 10, lines 20-22 show a ratio of thickness to spacing of 1.5 (0.15mm thick paste at 0.1mm spacing), which is in accordance with the "at least 0.5" limit recited now in claims 1, 13, and 24. The ratio claimed by Applicant is explicitly recited on page 11, lines 2-4. Applicant supports this limitation by way of examples described commencing on page 11, line 13 to page 12, line 17. The thickness of the solder is needed at pads for large components, but the methods and materials used prevent solder shorts with the thick paste between closely spaced pads.

The Applicants believe that the subject application, as amended, is in condition for allowance. Such action is earnestly solicited by the Applicants.

In the event that the Examiner deems the present application non-allowable, it is requested that the Examiner telephone the Applicant's attorney or agent at the number indicated

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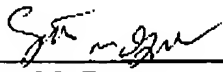
below so that the prosecution of the present case may be advanced by the clarification of any continuing rejection.

The Commissioner is hereby authorized to charge any fee due, or credit any overpayment, to Motorola, Inc., Deposit Account Number 50-2117.

Respectfully submitted,

SEND CORRESPONDENCE TO:

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